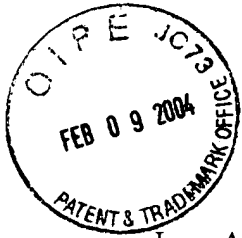


Image 2858



PATENT
YO996-184 IBM-219

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of : D.Y.Shih, et al.
Serial Number : 09/254,769
Filing Date : March 11, 1999
Examiner : V. Nguyen
Group Art Unit : 2858
For : WAFER SCALE HIGH DENSITY
PROBE ASSEMBLY ,
APPARATUS FOR USE THEREOF
AND METHODS OF
FABRICATION THEREOF

Honorable Commissioner of Patents
and Trademarks
Post Office Box 1450
Alexandria, VA 22313-1450

Sir:

In response to the Official Action dated January 5, 2004, please consider the following remarks with respect to the above-identified application as follows:

REMARKS

The present invention relates to a method for making an inter-connector to couple an electric module to a circuit board. The invention provides a probe structure that is an integral part of the fan-out wiring on the test substrate or other printed wiring means to minimize the electrical conductor length as well as contact resistance of the probe interface. The probe is provided with a compliant interface to compensate for slight variations in the rigid bond pad heights on the IC device and variations in the height of the probe contacts.